ABSTRACT

PEELING DEVICE FOR CHIP DETACHMENT

A peeling device is provided for detachment of a chip from an adhesive tape on which it is mounted. The device comprises a platform including a first surface and a raised contact surface set at a determinate height with respect to the first surface. The raised contact surface has a width that is smaller than a width of the chip for contacting the adhesive tape at a position of the chip. Further, an elevation device is projectable from the raised contact surface and movable with respect to the platform for lifting the chip away from the adhesive tape.

(FIG. 2(b))